

EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR SEALING AND SEMICONDUCTOR DEVICE

ABSTRACT

An epoxy resin composition used for sealing semiconductor devices, comprising as essential components:

- (A) An inorganic filler, with an amount of 75-95% by weight based on the total resin composition
- (B) An epoxy resin
- (C) A phenolic resin curing agent
- (D) A curing accelerator
- (E) A dispersing agent of ammonia type, in an amount of 0.1-0.5% by weight based on total epoxy resin composition.